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Claim Listing

1-22.(cancelled)

23.(previously presented) A semiconductor chip package, comprising:
a semiconductor chip having a first surface and a second surface perpendicular to and intersecting the first surface;
conductive leads electrically connected to and extending along the first surface of the chip at least to the intersection of the first and second surfaces;
a continuous body of encapsulating material substantially encapsulating the chip and the conductive leads; and
solder balls each having a first portion disposed in the encapsulating material and contacting a conductive lead and a second portion protruding from the encapsulating material.

24.(previously presented) A semiconductor chip package, comprising:
a semiconductor chip having a first surface and a second surface perpendicular to and intersecting the first surface and bond pads aligned along the first surface of the chip;
insulating material on the surface of the chip, the insulating material having holes therein to enable electrical connection to the bond pads;
conductive leads attached to the insulating material, each lead electrically connected to the bond pads and each lead extending along the first surface of the chip at least to the intersection of the first and second surfaces;
a continuous body of encapsulating material, discrete from the insulating material, substantially encapsulating the chip and the conductive leads; and
solder balls each having a first portion disposed in the encapsulating material and contacting a conductive lead and a second portion protruding from the encapsulating material.

Response To Office Action -2-

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